

We thank you for your order and are pleased to confirm it to you as follows

6 May 2021

Administrative details

Your references

Order nr.	E1311610	Purchase reference	EDCPSUr15_may21
Service	BINDI pool	Project reference	EDCPSUr15
Board name	EDCPSUr15	Article number	EDCPSUr15
Repeat order	E1291390		

Invoicing & delivery details

Invoice to:

EXINOM CORE SL
DAVID GARRIDO
CALLE ARANJUEZ, 513
28805 ALCALA DE HENARES
Spain
+00 (34) 699850012
reozen@gmail.com

Delivered to:

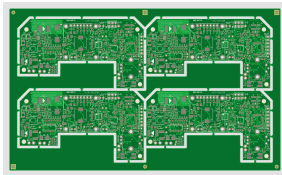
EXINOM CORE SL
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PCB

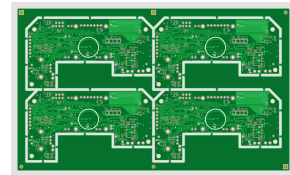
PCB Visualizer

PCB images

Top view :

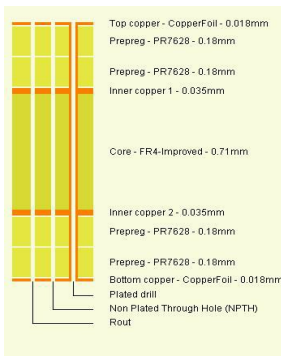


Bottom view :



Buildup & Mechanical plan

Board buildup :



Technology & options

Board definition

Number of layers	4	Delivery format	Eurocircuits, according to customer specific rules
PCB width (X)	0 mm	PCB height (Y)	0 mm
eC-registration compatible	No		

Panel definition

Panel width	210 mm	Panel height	124 mm
Horizontal (X) PCB separation method	Breakrouting	Vertical (Y) PCB separation method	Breakrouting
Panel without cross outs	No	Panel outline	Routed

Board definition

Top soldermask	Green	Bottom soldermask	Green
Top legend	White	Bottom legend	White
Surface finish	HAL		
	Leadfree		
Bare board testing	Yes		

Board technology

Pattern class	6	Drill class	Drill C
Outer layer trackwidth (OL-TW)	0.150 mm	Hole density	< 1000/dm2
Outer layer isolation distance (OL-TT-TP-PP)	0.150 mm	Holes <= may be reduced	0.45 mm
Outer layer annular ring (OAR)	0.125 mm		
Inner layer trackwidth (IL-TW)	0.150 mm		
Inner layer isolation distance (IL-TT-TP-PP)	0.150 mm		
Inner layer annular ring (IAR)	0.125 mm		

Material definition

Board thickness	1.55 mm	Board buildup	Standard buildup
Base material	FR4IMP	Material Tg	145-150°C
Outer layer copper foil	18µm(End-Cu +/-35µm)	Inner layer copper foil	35µm
Extra PTH runs	0	Extra press cycles	0
Reversed buildup	No	Inner layer core thickness	Standard

Advanced options

Milling	No	Peelable mask	No
Edge connector gold surface mm²	0	Edge connector bevelling	No
Copper up to board edge	No	Plated holes on the board edge	No
Carbon contacts	No	Viafill	No
Top heatsink paste	No	Bottom heatsink paste	No
Specific tolerances	No	Specific marking	No
Press-fit holes	No	Depth routing	No
Round-edge plating	No	Chamfered mechanical holes	No
Cross section report required	No		

Pricing

Printed circuits

Order nr.	Shipment date	Quantity	Unit price	Transport price	Transport mode	Total price	VAT	Gross
E1311610	7 June 2021	250	7.96 EUR	33.01 EUR	Express	2023.01 EUR	0.0 %	2023.01 EUR

Payment terms & conditions

The payment term is 30 days from invoice date. All our deliveries are according to our general terms and conditions of delivery. These are available on the website , and agreed upon between us during the registration procedure. The final quantity to be delivered can vary up to 5% of the ordered quantity. Delivery terms start counting upon receipt of the complete documentation and firm order.